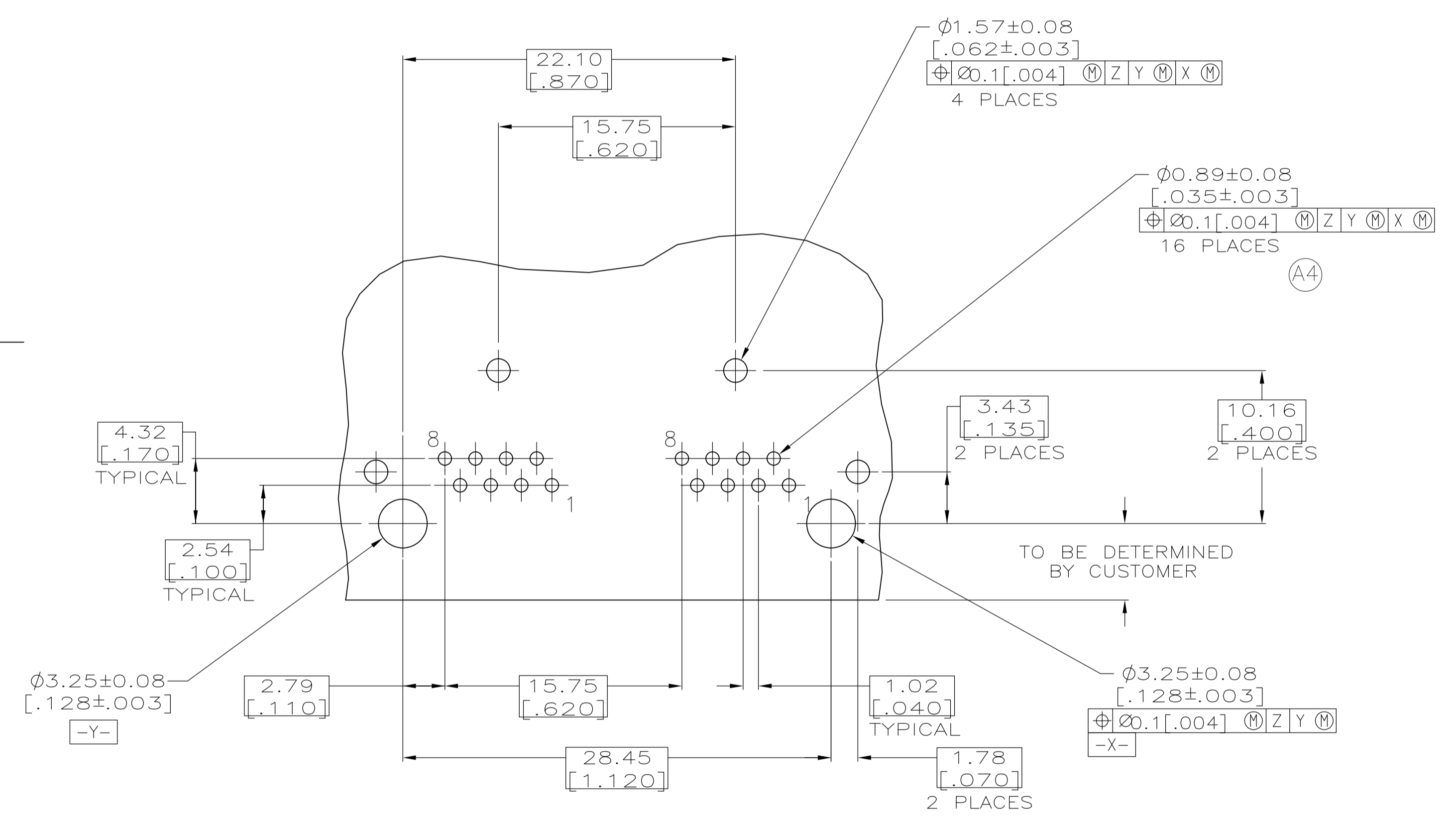
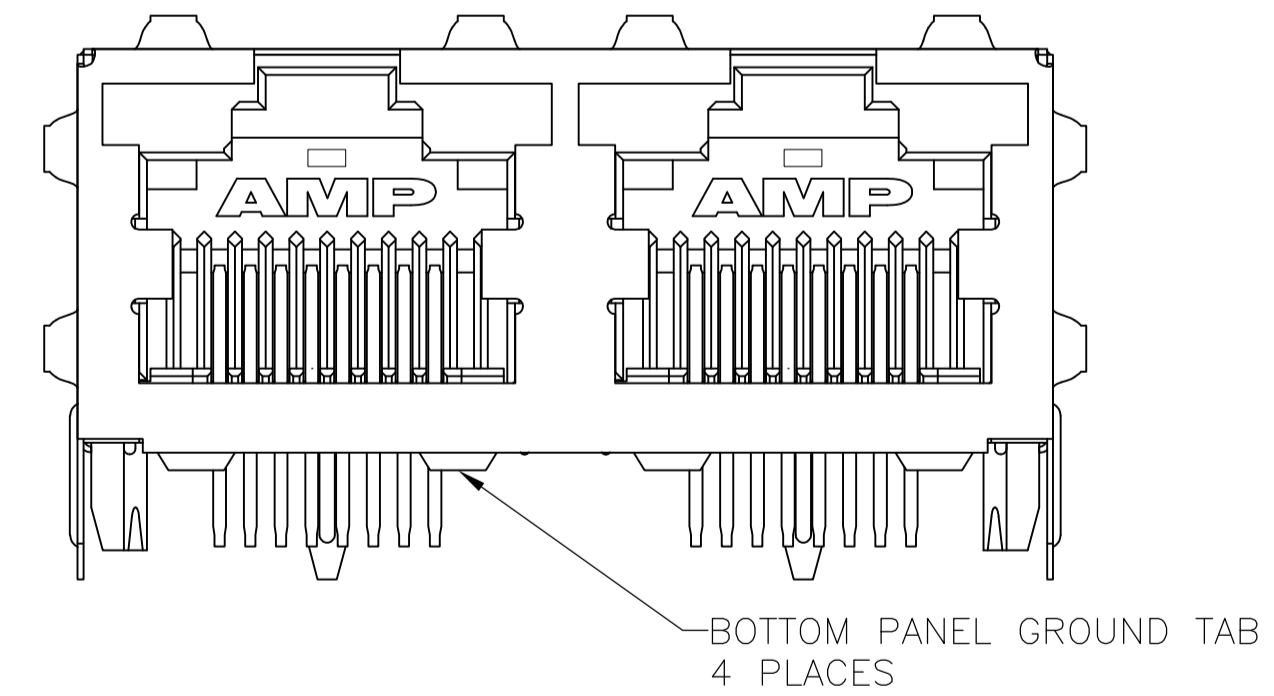


- MATERIAL: HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27 µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27 µm [.000050] MINIMUM THICK NICKEL. SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27 µm [.000050] MINIMUM SATIN NICKEL WITH 2.03 µm [.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
 - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- ⚠ SUGGESTED PANEL OPENING DIMENSIONS.
 ⚠ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
 ⚠ THE PART IS PRELIMINARY.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)

PN 6368459-4
 SAME AS PN 6368459-3
 EXCEPT AS SHOWN WITH BOTTOM GROUND PANEL TAB

PANELL GROUND TAB	DIM. A	PART NUMBER
W BOTTOM PANEL GROUND TAB	3.68 [.145]	6368459-4
W/O BOTTOM PANEL GROUND TAB	3.68 [.145]	6368459-3
W/O BOTTOM PANEL GROUND TAB	3.05 [.120]	6368459-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DIN D.L.MAYER 17APR2005	Tyco Electronics Corporation Harrisburg, Pa 17105-3608
0 PLC ± -	1 PLC ± -	CIK J.WESTMAN 17APR2005	
2 PLC ± 0.25[.01]	3 PLC ± 0.13[.005]	APVD S.FLICKINGER 17APR2005	Tyco Electronics INVERTED MODULAR JACK ASSEMBLY, 1X2, SHIELDED, PANEL GROUND
4 PLC ± -	ANGLES ± -	PRODUCT SPEC 108-1163-4	
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	APPLICATION SPEC 114-2154	SIZE CAGE CODE DRAWING NO. RESTRICTED TO
		WEIGHT -	A1 00779 C=6368459 -
		CUSTOMER DRAWING	SCALE 4:1 SHEET 1 OF 1 REV A4